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**Semiconductor devices – Micro-electromechanical devices –
Part 43: Test method of electrical characteristics after cyclic bending
deformation for flexible micro-electromechanical devices**

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MICRO-ELECTROMECHANICAL DEVICES –**
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IEC 62047-43 has been prepared by subcommittee 47F: Micro-electromechanical devices, of IEC technical committee 47: Semiconductor devices. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
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Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

A list of all parts in the IEC 62047 series, published under the general title *Semiconductor devices – Micro-electromechanical devices*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn, or
- revised.

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INTRODUCTION

In the recent trend toward ubiquitous sensor society and the world of internet of things, demand and thus the market for softer electronic devices are quickly expanding. That is what flexible micro-electromechanical devices are for, some of which are already released into the market. Even a so-called foldable device is under development and will soon appear in the market. However, to operate trillions of such devices for the comfort and safety of human beings, the reliability of the individual devices is a critical concern. Especially in the case of flexible devices, robustness against bending deformation is an important issue which will be shared among all the producers and users of such devices. In addition, since such devices are bent usually not only once but some numbers of cycles, information on performance deterioration along with the number of cycles is also important.

In order to understand how safe a situation is, even after numbers of cycles, performance deterioration behaviour of those devices as a function of loading levels and cycles needs to be evaluated so as to ensure secure operation during expected service periods. This standard procedure of testing is designed with the emphasis on such points and with the applicability not only to already emerging flexible devices but also to so-called foldable devices which still function even when the device is folded.

SEMICONDUCTOR DEVICES – MICRO-ELECTROMECHANICAL DEVICES –

Part 43: Test method of electrical characteristics after cyclic bending deformation for flexible micro-electromechanical devices

1 Scope

This part of IEC 62047 specifies the test method of electrical characteristics after cyclic bending deformation for flexible electromechanical devices. These devices include passive micro components and active micro components on the flexible film or embedded in the flexible film. The desired in-plane dimensions of the device for the test method ranges typically from 1 mm to 300 mm and the thickness ranges from 10 μm to 1 mm, but these are not limiting values. The test method is so designed as to understand and further visualize the entire performance deterioration behaviour after cyclic bending deformation in a concept of 3D (P-S-N: Performance – Severity of bending – Number of cycles) plot over the loading space of severity of bending and number of repeated cycles. This document is essential to estimate safety margin over the operation period under a certain level of cyclic bending deformation and indispensable for reliable design of the product employing these devices.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 62047-35:2019, *Semiconductor devices – Micro-electromechanical devices – Part 35: Test method of electrical characteristics under bending deformation for flexible electro-mechanical devices*